(C) 30 to 700 parts by weight of an electrically conductive powder having a construction comprising an inorganic filler or a resin particle covered with a nickel layer which in turn is covered with a gold layer,

(D) 0.1 to 20 parts by weight of an adhesive aid, and

(E) a curing agent in an amount sufficient to cure the organopolysiloxane.

Please add the following claims:

--10. The silicone rubber composition of claim 1, wherein the metal-plated powder has a silicon-based polymeric compound with a reducing property between the inorganic filler or resin and the nickel.

11. The silicone rubber composition of claim 3, wherein the metal-plated silica powder has a silicon-based polymeric compound with a reducing property between the silica and the nickel.

12. The silicone rubber composition of claim 11, wherein the silicon-based polymeric compound with a reducing property is one selected from the group consisting of polysilanes, polycarbosilanes, polysiloxanes and polysilazanes having silicon-silicon or silicon-hydrogen bonds.

13. The silicone rubber composition of claim 3, wherein the metal-plated silica powder has a ceramic between the silica and the nickel formed by heat treating a silicon-based compound with a reducing property between the silica and the nickel in the presence of an inert gas at a temperature of at least 200°C to convert the silicon-based polymeric compound to the ceramic.

14. The silicone rubber composition of claim 1, wherein component (C) is a powder having an average particle size within a range of 0.05 to 100 $\mu$m.

15. The silicone rubber composition of claim 1, wherein component (C) is a powder having an average particle size within a range of 0.1 to 10 $\mu$m.

16. The silicone rubber composition of claim 1, wherein component (C) is a powder having a specific surface area of at most 1 $m^2/g$.

17. The silicone rubber composition of claim 1, wherein component (C) is present in an amount of 50 to 600 parts by weight.--